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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 2812 Raaijmakers et al. Applicant 09/764,711 App. No. January 18, 2001 Filed METHOD OF DEPOSITING For SILICON WITH HIGH STEP **COVERAGE**

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

Examiner

Enclosed is form PTO-1449 listing 5 references that are also enclosed. This Information Disclosure Statement is being filed under 37 C.F.R. § 1.97(c)(2) before the mailing date of a final action and before the mailing of a Notice of Allowance. This Statement is accompanied by the fees set forth in 37 C.F.R. § 1.17(p). The Commissioner is hereby authorized to charge any additional fees which may be required or to credit any overpayment to Account No. 11-1410.

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Respectfully submitted,

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Dated: January 24,200

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| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | APPLICANT Raaijmakers et al. | | | |
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| U.S. PATENT DOCUMENTS | | | | | | |
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